Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2	(("4344006") or ("5641997")).PN.	USPAT; USOCR	OR	OFF	2005/08/27 10:15
L2	5	"0590975"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/27 10:16
L3	1	"00590975"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/27 10:17
L4	19	"590975"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/27 10:37
L5	22557	(adhesiv$5 with spray$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/27 10:43
L6	23639	(adhesiv$5 with filler)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/27 10:38
L7	169294	(adhesiv$5 with resin)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/27 10:40
L8	889	5 and 6 and 7	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/27 10:41
L9	305	8 and color$5 and visco$9	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/27 10:41
L10	129	9 and (epox$5 near5 resin)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/27 10:42

L11	13927	(adhesiv$5 near5 spray$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/27 10:44
L12	46	10 and 11	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/27 10:45
L13	6	(adhesiv$5 near5 spray$5) same (adhesiv$5 near5 filler) same (adhesiv$5 near5 resin)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/27 10:47
L14	218	(adhesiv$5 near5 spray$5) and ((adhesiv$5 with filler) same (adhesiv$5 with resin))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/27 10:48
L15	4	14 and (filler with (color colour)) and visco$9	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/27 10:57
L16	31	(laser with mark$5 with (semiconduct$5 die silicon wafer) with adhesive)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/27 10:58
L18	3	16 and (adhesiv$5 with spray$5 with filler)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/27 11:08
L19	3	(laser near9 mark$5) and (adhesiv$5 with spray$5 with filler)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/27 11:09
L20	51	(laser near9 mark$5) and (adhesiv$5 with filler)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/27 11:14
L22	10	(laser near9 mark$5) and (adhesiv$5 with filler) and (laser with adhesiv$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/27 11:15

L23	4	(laser near9 mark$5) and (adhesiv$5 with filler) and (laser with adhesiv$5) and (mark$5 with filler)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/27 11:16
L24	4	(laser near9 mark$5) and (adhesiv$5 with filler) and (laser with adhesiv$5) and (laser with filler)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/27 11:19
L25	94	(laser near9 mark$5) and (laser with adhesiv$5) and (mark$5 with (semiconductor silicon die wafer))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/27 11:20
L26	42	((laser near9 mark$5) same (laser with adhesiv$5)) and (mark$5 with (semiconductor silicon die wafer))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/27 11:20
L27	40	((laser near9 mark$5) with (laser with adhesiv$5)) and (mark$5 with (semiconductor silicon die wafer))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/27 11:20